

## Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

[Aluminum PCB manufacturers](#)

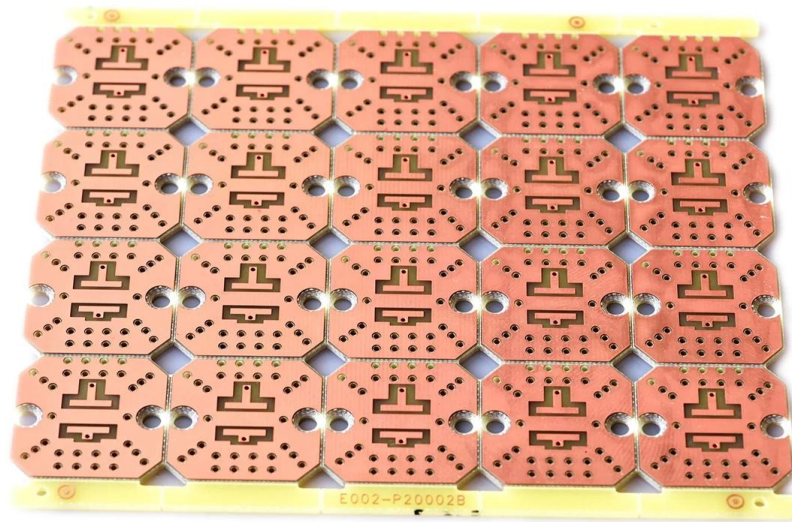
COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK THESE FOR MORE INFORMATION [Aluminum Printed Circuit Boards in China](#)

## Product Description

PCB P/N	LE-500V1
Layer Count	1L
Material	Base Ceramics
Board thk	1.6mm
copper thk	1oz
Smallest hole size	2.0mm
No. of holes (pcs)	16
line w/s	20/20mil
Impedance control. Y / N (Tol %)	N
Surface Finishing	ENIG( Au:0.05um)
Solder Mask Silkscreen	White / Black
Single board size	Dim X (mm):Dim X (mm):100;Dim Y (mm):115
Panelisation	Dim X (mm):100;Dim Y (mm):115;No Of UPS:1
Special:peelable mask	N
Routing/Punching	CNC + Countersunk Head screw



[www.o-leading.com](http://www.o-leading.com)

[High Quality Aluminum PCB manufacturer](#)

Our Team





Certifications



UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354  
Wiring, Printed - Component

For enhanced search functionality, please visit UL's [ICD Family of Databases](#).  
Click on a product designation for complete information.

Page Bottom

Wiring, Printed - Component

See General Information for Wiring, Printed - Components

O-LEADING SUPPLY CHAIN CO LIMITED E490354  
Fortune Building, Nanheng West Road  
Room 1313  
Huizhou, Guangdong 516211 CHINA

	Cond Width			SS/ DS/ Di	Area Diam	Max		Flame	Meets UL796	C	
	Min	Max	Edge			Solder	Diper				
Typ	max(in)	mm(in)	mic(mil)	DS0	mm(in)	C	sec	C	Class	DSR	I
<b>Multi-layer (mass laminate) printed wiring boards.</b>											
<b>D-LEADING-401</b>											
	0.1 (0.004)	0.5 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	-
<b>D-LEADING-407</b>											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.2 (0.4)	260	10	130	V-0	NI	-
<b>Multi-layer printed wiring boards.</b>											
<b>D-LEADING-408</b>											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) mi-135	DS	50.8 (2.0)	260	20	130	V-0	NI	1
<b>Single layer printed wiring boards.</b>											
<b>D-LEADING-002</b>											
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	NI	-
<b>D-LEADING-003</b>											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	▲	-
<b>D-LEADING-033</b>											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	NI	-
<b>D-LEADING-205</b>											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	NI	-
<b>D-LEADING-206</b>											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	NI	-

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.  
Last updated on 2017-01-27

Questions? [Print this page](#) [Terms of Use](#) [Page Top](#)



Test Results:

Test Part Description:

Specimen No. **SGS Sample ID Description**  
SNI1 CAN18-051647.001 Green PCB\*

Remarks:

(1) 1 mg/kg = 1 ppm = 0.0001%  
(2) MDL = Method Detection Limit  
(3) ND = Not Detected (< MDL)  
(4) \* = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-6:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Items	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Monobromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Monobromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



Member of the SGS Group (SGL SA)

## Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



## FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up  
Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching →  
Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.